EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	23	257/E23.062	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/29 19:14
L2	4	("20010003049" | "20020001937" | "6191483" | "6418615").PN. OR ("7196426").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/29 19:17
L3	26	("5321210" | "5322593" | "5337466" | "5426849" | "5590461" | "5628852" | "5686702" | "5745984" | "6049123" | "6214641").PN. OR ("6418615").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/29 19:19
L4	16	("4978639" | "5055321" | "5260518" | "5826330" | "6217987" | "6242079" | "6251502" | "6376049" | "6410858" | "6418615").PN. OR ("6591495").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/29 19:22
L5	106	257/E23.069	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/29 19:24
L6	18	("20030011442" | "20030095014" | "20030151133" | "20040027813" | "20040178854" | "20050258548" | "20060103003" | "20060134405" | "20060175712" | "5522132" | "5602672" | "6127901" | "6329715" | "6369324" | "6384701" | "6911734" | "6933596" | "7064627").PN. OR	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/29 19:27

		("7294904").URPN.				
L7	78	("20010040006" | "20010050441" | "20020011662" | "20020021560" | "20020027773" | "20020074653" | "20020076919" | "20020185308" | "20030015783" | "20030038366" | "20030110452" | "20040007750" | "20040027813" | "20040056341" | "20040183193" | "20040190274" | "20040227258" | "20040256738" | "20050002167" | "20050051903" | "20050100298" | "20050127489" | "20050258509" | "20060022333" | "4598307" | "5239198" | "5498906" | "5608262" | "5655290" | "5708296" | "5789303" | "5798567" | "5814871" | "5818748" | "5838551" | "5847951" | "5854534" | "5886408" | "5898223" | "5926061" | "5935404" | "5939782" | "5940278" | "5963110" | "5977640" | "6018192" | "6054008" | "6218729" | "6219254" | "6235996" | "6294408" | "6313521" | "6330164" | "6346743" | "6362525" | "6366467" | "6369443" | "6370010" | "6370013" | "6380798" | "6400575" | "6400576" | "6404649" | "6413353" | "6417463" | "6489574" | "6518666" | "6525414" | "6534855" | "6535398" | "6812078"	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/29 19:30

			"6838763" | "6879491" | "6888218" | "6907658" | "6949822" | "6952049").PN. OR ("7247932").URPN.				
L8	2	("4990996" | "5598036").PN. OR ("7227268").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/29 19:33
L9	1	"20060076695"	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/29 19:45
L10	23	257/E21.504	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/29 20:00
L11	0	257/23.07	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/29 20:03
L12	36	257/E23.07	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/29 20:03
L13	6424	257/778	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/29 20:03
L14	15	("5637920" | "5717245" | "5973928" | "5982633" | "6008532" | "6057596" | "6064113" | "6075285" | "6114769" | "6235997" | "6414386" | "6448639" | "6522173" | "6538336" | "6680544").PN. OR ("7298040").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/29 20:05
L15	51	("5545923" | "5686699").PN. OR ("6064113").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/29 20:11

L16	25	("4746966" | "5632631" | "5641988" | "5796169" | "5895968").PN. OR ("6057596").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/29 20:12
L17	14	("5598036" | "5640047" | "5703402" | "5894410" | "6057596" | "6137168" | "6163071" | "6201302" | "6242815").PN. OR ("6403896").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/29 20:16
L18	47	("5216278" | "5285352" | "5355283" | "5450283" | "5490324").PN. OR ("5894410").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/29 20:20
L19	65	("4598166" | "5450290" | "5475264" | "5477933" | "5741729" | "5790384" | "5952726" | "5953213" | "5994766" | "6008534" | "6064113" | "6075710" | "6111756").PN. OR ("6198635").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/29 20:28
L20	3262	257/786	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/29 20:28
L21	524	257/729	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/29 20:48
L22	3328	257/712	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/29 21:33

S1	18	"5731047".pn. or "5836063".pn. or "5841075".pn. or "5868950".pn. or "5888630".pn. or "5888631".pn. or "5900312".pn. or "5983974".pn. or "6011697".pn. or "6018196".pn. or "6021564".pn. or "6103992".pn. or "6127250".pn. or "6143401".pn. or "6183592".pn. or "6203891".pn. or "6248959".pn. or "20040012938".pn.	US-PGPUB; USPAT	OR	OFF	2005/06/21 03:52
S2	1	"3953566".PN.	USPAT; USOCR	OR	OFF	2004/11/09 19:25
S3	1	"4482516".PN.	USPAT; USOCR	OR	OFF	2004/11/09 19:26
S4	1	"4591659".PN.	USPAT; USOCR	OR	OFF	2004/11/09 19:26
S5	1	"4591659".PN.	USPAT; USOCR	OR	OFF	2004/11/09 19:26
S6	1	"4654248".PN.	USPAT; USOCR	OR	OFF	2004/11/09 19:26
S7	1	"4654248".PN.	USPAT; USOCR	OR	OFF	2004/11/09 19:27
S8	1	"4705762".PN.	USPAT; USOCR	OR	OFF	2004/11/09 19:27
S9	1	"4890194".PN.	USPAT; USOCR	OR	OFF	2004/11/09 19:27
S10	1	"4890194".PN.	USPAT; USOCR	OR	OFF	2004/11/09 19:28
S11	1	"4943844".PN.	USPAT; USOCR	OR	OFF	2004/11/09 19:28
S12	1	"4985296".PN.	USPAT; USOCR	OR	OFF	2004/11/09 19:28
S13	1	"5103293".PN.	USPAT; USOCR	OR	OFF	2004/11/09 19:29
S14	1	"5339217".PN.	USPAT; USOCR	OR	OFF	2004/11/09 19:29
S15	1	"5455385".PN.	USPAT; USOCR	OR	OFF	2004/11/09 19:29
S16	1	"5506756".PN.	USPAT; USOCR	OR	OFF	2004/11/09 19:29
S17	1	"5103293".PN.	USPAT; USOCR	OR	OFF	2004/11/09 19:31

S18	1	"5339217".PN.	USPAT; USOCR	OR	OFF	2004/11/09 19:31
S19	1	"5455385".PN.	USPAT; USOCR	OR	OFF	2004/11/09 19:32
S20	1	"5506756".PN.	USPAT; USOCR	OR	OFF	2004/11/09 19:32
S21	1	"5532513".PN.	USPAT; USOCR	OR	OFF	2004/11/09 19:32
S22	1	"5545473".PN.	USPAT; USOCR	OR	OFF	2004/11/09 19:32
S23	1	"5545473".PN.	USPAT; USOCR	OR	OFF	2004/11/09 19:33
S24	1	"5572405".PN.	USPAT; USOCR	OR	OFF	2004/11/09 19:33
S25	6	"6046910".pn. or "6210862".pn. or "6570245".pn. or "20010030057".pn. or "20020007964".pn. or "20020135063".pn.	US-PGPUB; USPAT	OR	OFF	2004/11/09 19:38
S26	69208	(semiconductor or chip or die or IC) and (interposer or interconnect or redistribution)	US-PGPUB; USPAT	OR	OFF	2004/11/09 19:39
S27	49710	(semiconductor or chip or die or IC) and (interposer or interconnect or redistribution)	USPAT	OR	OFF	2004/11/09 20:01
S28	7330	S27 and (ball or bump)	USPAT	OR	OFF	2004/11/09 19:41
S29	30	S28 and (interposer or interconnect or redistribution) with (metal or protect$3) with bottom near surface	USPAT	OR	OFF	2004/11/09 19:45
S30	72	S28 and (interposer or interconnect or redistribution) with (layer or film) with bottom near surface	USPAT	OR	OFF	2004/11/09 20:02
S31	1	"6285081".PN.	USPAT; USOCR	OR	OFF	2004/11/09 19:50
S32	154740	(semiconductor or chip or die or IC) and (interposer or interconnect or redistribution or carrier)	USPAT	OR	OFF	2004/11/09 21:29

S33	16949	(semiconductor or chip or die or IC) and (interposer or interconnect or redistribution or carrier) and (ball or bump)	USPAT	OR	OFF	2004/11/09 20:02
S34	72	S33 and (interposer or interconnect or redistribution) with (layer or film) with bottom near surface	USPAT	OR	OFF	2004/11/09 20:02
S35	138	S33 and (interposer or interconnect or redistribution or carrier) with (layer or film) with bottom near surface	USPAT	OR	OFF	2004/11/09 20:14
S36	6149	S33 and "257"/$.ccls.	USPAT	OR	OFF	2004/11/09 20:15
S37	4247	S33 and (flip near chip or "C4")	USPAT	OR	OFF	2004/11/09 20:15
S38	3001	S37 and "257"/$.ccls.	USPAT	OR	OFF	2004/11/09 20:49
S39	292	S37 and 257/666	USPAT	OR	OFF	2004/11/09 20:16
S40	11863	S33 and (heatsink or heat neat (sink or stiffener or spreader or transfer) or ground near (plane or film or layer))	USPAT	OR	OFF	2004/11/09 20:19
S41	3868	S33 and (heatsink or heat neat (sink or stiffener or spreader or transfer) or ground near (plane or film or layer)) with surface	USPAT	OR	OFF	2004/11/09 20:19
S42	340	S33 and (heatsink or heat neat (sink or stiffener or spreader or transfer) or ground near (plane or film or layer)) with bottom near surface	USPAT	OR	OFF	2004/11/09 20:19
S43	6149	S33 and "257"/$.ccls.	USPAT	OR	OFF	2004/11/09 20:42
S44	90	S33 and prevent$3 near warp$3	USPAT	OR	OFF	2004/11/09 20:43
S45	1257	S37 and (257/778 or 257/786 or 257/798)	USPAT	OR	OFF	2004/11/09 20:50
S46	2	"3290564".PN.	USPAT; USOCR	OR	OFF	2004/11/09 21:19

S47	1	"4654248".PN.	USPAT; USOCR	OR	OFF	2004/11/09 21:20
S48	1	"4893172".PN.	USPAT; USOCR	OR	OFF	2004/11/09 21:20
S49	1	"4942076".PN.	USPAT; USOCR	OR	OFF	2004/11/09 21:20
S50	1	"5086337".PN.	USPAT; USOCR	OR	OFF	2004/11/09 21:20
S51	1	"5216278".PN.	USPAT; USOCR	OR	OFF	2004/11/09 21:21
S52	1	"5325265".PN.	USPAT; USOCR	OR	OFF	2004/11/09 21:21
S53	1	"5338967".PN.	USPAT; USOCR	OR	OFF	2004/11/09 21:21
S54	1	"5473119".PN.	USPAT; USOCR	OR	OFF	2004/11/09 21:21
S55	1	"5481136".PN.	USPAT; USOCR	OR	OFF	2004/11/09 21:22
S56	1	"5493153".PN.	USPAT; USOCR	OR	OFF	2004/11/09 21:22
S57	1	"5572070".PN.	USPAT; USOCR	OR	OFF	2004/11/09 21:22
S58	1	"5574630".PN.	USPAT; USOCR	OR	OFF	2004/11/09 21:22
S59	1	"5610442".PN.	USPAT; USOCR	OR	OFF	2004/11/09 21:22
S60	1	"5714803".PN.	USPAT; USOCR	OR	OFF	2004/11/09 21:22
S61	1	"5744863".PN.	USPAT; USOCR	OR	OFF	2004/11/09 21:23
S62	1	"5777386".PN.	USPAT; USOCR	OR	OFF	2004/11/09 21:23
S63	1	"5786635".PN.	USPAT; USOCR	OR	OFF	2004/11/09 21:23
S64	15	(semiconductor or chip or die or IC) and (interposer or interconnect or redistribution or carrier) with spacer with (ball or bump)	USPAT	OR	OFF	2004/11/09 21:31
S65	192	(semiconductor or chip or die or IC) and (interposer or interconnect or redistribution or carrier) with spac$3 with (ball or bump)	USPAT	OR	OFF	2004/11/09 21:31

S66	94	(molding or encapsulat$3) with bottom near surface with (adhesive or glue)	USPAT	OR	ON	2004/11/10 22:48
S67	492	(molding or encapsulat$3) with attach$3 with (board or "PCB")	USPAT	OR	ON	2004/11/10 22:49
S68	1	"5285352".PN.	USPAT; USOCR	OR	OFF	2004/11/10 23:22
S69	1	"5365400".PN.	USPAT; USOCR	OR	OFF	2004/11/10 23:22
S70	1	"5455462".PN.	USPAT; USOCR	OR	OFF	2004/11/10 23:23
S71	1	"5559369".PN.	USPAT; USOCR	OR	OFF	2004/11/10 23:23
S72	1	"5617294".PN.	USPAT; USOCR	OR	OFF	2004/11/10 23:23
S73	1	"5642261".PN.	USPAT; USOCR	OR	OFF	2004/11/10 23:24
S74	1	"5650593".PN.	USPAT; USOCR	OR	OFF	2004/11/10 23:24
S75	1	"5734555".PN.	USPAT; USOCR	OR	OFF	2004/11/10 23:24
S76	1	"5736785".PN.	USPAT; USOCR	OR	OFF	2004/11/10 23:25
S77	1	"5856911".PN.	USPAT; USOCR	OR	OFF	2004/11/10 23:25
S78	1	"5861670".PN.	USPAT; USOCR	OR	OFF	2004/11/10 23:25
S79	1	"5877552".PN.	USPAT; USOCR	OR	OFF	2004/11/10 23:26
S80	1	"5977626".PN.	USPAT; USOCR	OR	OFF	2004/11/10 23:26
S81	1	"6191360".PN.	USPAT; USOCR	OR	OFF	2004/11/10 23:26
S82	0	"6534723".pn. and polyimide with resist	USPAT	OR	OFF	2004/11/10 23:40
S83	1	"6534723".pn.	USPAT	OR	OFF	2004/11/10 23:40
S84	1	"6534723".pn. and polyimide and resist	USPAT	OR	OFF	2004/11/10 23:40
S85	13	174/255 and polyimide with solder near resist	USPAT	OR	OFF	2004/11/10 23:41

S86	658	(semiconductor or die or chip or IC) and (interposer or interconnect$3 or redistribut$3) with (spacer or pad) with (ball or bump)	USPAT	OR	OFF	2004/11/11 21:48
S87	1	"5229643".PN.	USPAT; USOCR	OR	OFF	2004/11/11 22:04
S88	1	"5554887".PN.	USPAT; USOCR	OR	OFF	2004/11/11 22:05
S89	1	"5903052".PN.	USPAT; USOCR	OR	OFF	2004/11/11 22:05
S90	1	"5920117".PN.	USPAT; USOCR	OR	OFF	2004/11/11 22:05
S91	1	"6184580".PN.	USPAT; USOCR	OR	OFF	2004/11/11 22:05
S92	1	"6219243".PN.	USPAT; USOCR	OR	OFF	2004/11/11 22:06
S93	1	"6259156".PN.	USPAT; USOCR	OR	OFF	2004/11/11 22:06
S94	1	"5136365".PN.	USPAT; USOCR	OR	OFF	2004/11/11 22:20
S95	1	"5187020".PN.	USPAT; USOCR	OR	OFF	2004/11/11 22:20
S96	1	"5375042".PN.	USPAT; USOCR	OR	OFF	2004/11/11 22:21
S97	1	"5412539".PN.	USPAT; USOCR	OR	OFF	2004/11/11 22:36
S98	1	"5509200".PN.	USPAT; USOCR	OR	OFF	2004/11/11 22:37
S99	1	"5518674".PN.	USPAT; USOCR	OR	OFF	2004/11/11 22:37
S100	1	"5805426".PN.	USPAT; USOCR	OR	OFF	2004/11/11 22:37
S101	1	"5893765".PN.	USPAT; USOCR	OR	OFF	2004/11/11 22:37
S102	1	"5905638".PN.	USPAT; USOCR	OR	OFF	2004/11/11 22:37
S103	1	"5910641".PN.	USPAT; USOCR	OR	OFF	2004/11/11 22:37
S104	1	"6090633".PN.	USPAT; USOCR	OR	OFF	2004/11/11 22:38
S105	1	"6326561".PN.	USPAT; USOCR	OR	OFF	2004/11/11 22:38
S106	298	solder near (resist or mask) with polyimide	USPAT	OR	OFF	2004/11/11 23:19

S107	23	S106 and interposer	USPAT	OR	OFF	2004/11/11 23:20
S108	4	S106 and interposer with solder near (resist or mask)	USPAT	OR	OFF	2004/11/11 23:20
S109	19	S106 and (interposer or interconnect$3 or redistribut$3) with solder near (resist or mask)	USPAT	OR	OFF	2004/11/11 23:29
S110	1	"6600224".pn. and polyimide and adhesive and dielectric	USPAT	OR	ON	2004/11/11 23:28
S111	87	(interposer or interconnect$3 or redistribut$3) with adhesive with polyimide	USPAT	OR	OFF	2004/11/12 01:11
S112	4267	257/778	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/12 01:43
S114	3660	257/712	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/12 13:51
S115	2181	257/713	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/12 15:29
S116	3456	257/737	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/12 16:31
S117	363	257/338	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/12 16:31
S118	48835	(interpos$3 or interconnect$3 or redistribut$3) with (reference or ground)	US-PGPUB; USPAT	OR	ON	2005/06/21 03:53
S119	39061	(interpos$3 or interconnect$3 or redistribut$3) with (reference or ground)	USPAT	OR	ON	2005/06/21 03:54

S120	1847	(interpos$3 or interconnect$3 or redistribut$3) with (reference or ground) near plane	USPAT	OR	ON	2005/06/21 09:49
S121	506	(interpos$3 or interconnect$3 or redistribut$3) with (reference or ground) near layer	USPAT	OR	ON	2005/06/21 12:10
S122	1	"5113315".PN.	USPAT; USOCR	OR	OFF	2005/06/21 10:53
S123	1	"5741729".PN.	USPAT; USOCR	OR	OFF	2005/06/21 10:53
S124	1	"5851337".PN.	USPAT; USOCR	OR	OFF	2005/06/21 10:53
S125	1	"5898217".PN.	USPAT; USOCR	OR	OFF	2005/06/21 10:54
S126	1	"5933324".PN.	USPAT; USOCR	OR	OFF	2005/06/21 10:54
S127	1	"5959356".PN.	USPAT; USOCR	OR	OFF	2005/06/21 10:54
S128	1	"6198635".PN.	USPAT; USOCR	OR	OFF	2005/06/21 10:54
S129	1	"6362525".PN.	USPAT; USOCR	OR	OFF	2005/06/21 10:55
S130	1	"6479758".PN.	USPAT; USOCR	OR	OFF	2005/06/21 10:55
S131	1	"6525942".PN.	USPAT; USOCR	OR	OFF	2005/06/21 10:55
S132	1	"20020139571".PN.	US-PGPUB	OR	OFF	2005/06/21 10:57
S133	0	(interpos$3 or interconnect$3 or redistribut$3) with stress near relise	USPAT	OR	ON	2005/06/21 11:26
S134	178	(interpos$3 or interconnect$3 or redistribut$3) with stress near relief	USPAT	OR	ON	2005/06/21 11:36
S135	0	(interpos$3 or interconnect$3 or redistribut$3) with moint$3 near structure	USPAT	OR	ON	2005/06/21 11:36
S136	1131	(interpos$3 or interconnect$3 or redistribut$3) with mount$3 near structure	USPAT	OR	ON	2005/06/21 11:59

S137	4795	(interpos$3 or interconnect$3 or redistribut$3) with support$3 near structure	USPAT	OR	ON	2005/06/21 12:00
S138	682	(interpos$3 or interconnect$3 or redistribut$3) with support$3 near structure with (back or rear or opposite)	USPAT	OR	ON	2005/06/21 12:04
S139	1	(interpos$3 or interconnect$3 or redistribut$3) with (polyimide or insulat$3 or dielectric) with plain with (back or rear or opposite)	USPAT	OR	ON	2005/06/21 12:05
S140	20	(interpos$3 or interconnect$3 or redistribut$3) with (polyimide or insulat$3 or dielectric) with plain	USPAT	OR	ON	2005/06/21 12:07
S141	31	(interpos$3 or interconnect$3 or redistribut$3) same (polyimide or insulat$3 or dielectric) with plain	USPAT	OR	ON	2005/06/21 12:07
S142	11	S141 not S140	USPAT	OR	ON	2005/06/21 12:07
S143	13925	(interpos$3 or interconnect$3 or redistribut$3) with (spacer or stiffener or thermal near pad)	USPAT	OR	ON	2005/06/21 12:12
S144	13868	(interpos$3 or interconnect$3 or redistribut$3) with (spacer or stiffener)	USPAT	OR	ON	2005/06/21 12:12
S145	0	(interpos$3 or interconnect$3 or redistribut$3) with (spacer or stiffener or thermal near pad) and (spacer or stiffener or thermal near pad) with soder near mask	USPAT	OR	ON	2005/06/21 12:13

S146	3617	(interpos$3 or interconnect$3 or redistribut$3) with (spacer or stiffener or thermal near pad) and (spacer or stiffener or thermal near pad) with (rear or back or opposite)	USPAT	OR	ON	2005/06/21 12:13
S147	13260	(interpos$3 or interconnect$3 or redistribut$3) with spacer	USPAT	OR	ON	2005/06/21 12:13
S148	701	(interpos$3 or interconnect$3 or redistribut$3) with (stiffener or thermal near pad)	USPAT	OR	ON	2005/06/21 12:33
S149	3341	(semiconductor or die or dice or chip or IC) and (interpos$3 or interconnect$3 or redistribut$3) with (spacer)	USPAT	OR	ON	2005/06/21 12:34
S150	99	(semiconductor or die or dice or chip or IC) and (interpos$3 or interconnect$3 or redistribut$3) with (spacer) with pads	USPAT	OR	ON	2005/06/21 12:43
S151	1	"5136365".PN.	USPAT; USOCR	OR	OFF	2005/06/21 12:35
S152	1	"5187020".PN.	USPAT; USOCR	OR	OFF	2005/06/21 12:35
S153	1	"5375042".PN.	USPAT; USOCR	OR	OFF	2005/06/21 12:36
S154	1	"5412539".PN.	USPAT; USOCR	OR	OFF	2005/06/21 12:36
S155	1	"5509200".PN.	USPAT; USOCR	OR	OFF	2005/06/21 12:36
S156	1	"5518674".PN.	USPAT; USOCR	OR	OFF	2005/06/21 12:36
S157	1	"5805426".PN.	USPAT; USOCR	OR	OFF	2005/06/21 12:36
S158	1	"5893765".PN.	USPAT; USOCR	OR	OFF	2005/06/21 12:37
S159	1	"5905638".PN.	USPAT; USOCR	OR	OFF	2005/06/21 12:37
S160	1	"5910641".PN.	USPAT; USOCR	OR	OFF	2005/06/21 12:37

S161	1	"6090633".PN.	USPAT; USOCR	OR	OFF	2005/06/21 12:37
S162	1	"6326561".PN.	USPAT; USOCR	OR	OFF	2005/06/21 12:37
S163	1	"5893765".PN.	USPAT; USOCR	OR	OFF	2005/06/21 12:38
S164	1	"5905638".PN.	USPAT; USOCR	OR	OFF	2005/06/21 12:38
S165	1	"5910641".PN.	USPAT; USOCR	OR	OFF	2005/06/21 12:38
S166	1	"6090633".PN.	USPAT; USOCR	OR	OFF	2005/06/21 12:38
S167	469	(semiconductor or die or dice or chip or IC) and (interpos$3 or interconnect$3 or redistribut$3) with (adhesive) with pads	USPAT	OR	ON	2005/06/21 12:43
S168	64	(semiconductor or die or dice or chip or IC) and (interpos$3 or interconnect$3 or redistribut$3) with solid near (plain or layer)	USPAT	OR	ON	2005/06/21 13:12
S169	10	"6525942"	USPAT	OR	ON	2005/06/21 12:46
S170	352	(semiconductor or die or dice or chip or IC) and (interpos$3 or interconnect$3 or redistribut$3) with (ground or thermal) near (plain or layer)	USPAT	OR	ON	2005/06/21 13:07
S171	0	"6312266".pn. with (cover$3 or coat$3 or attach$3)	USPAT	OR	ON	2005/06/21 13:07
S172	32990	"6312266".pn. spacer with (cover$3 or coat$3 or attach$3)	USPAT	OR	ON	2005/06/21 13:08
S173	0	"6312266".pn. and spacer with (cover$3 or coat$3 or attach$3)	USPAT	OR	ON	2005/06/21 13:08
S174	0	"6312266".pn. and spacer with (cover$3) with (polyimide or epoxy)	USPAT	OR	ON	2005/06/21 13:09
S175	91	spacer with (cover$3) with (polyimide or epoxy)	USPAT	OR	ON	2005/06/21 13:09

S176	0	"6312266".pn. and spacer with underfill	USPAT	OR	ON	2005/06/21 13:09
S177	1	"6312266".pn. and spacer with epoxy	USPAT	OR	ON	2005/06/21 13:10
S178	1	"6312266".pn. and spacer with adhesive	USPAT	OR	ON	2005/06/21 13:10
S179	0	(semiconductor or die or dice or chip or IC) and (interpos$3 or interconnect$3 or redistribut$3) with spacer with under near fill and under near fill with (epoxy or polyimide)	USPAT	OR	ON	2005/06/21 13:12
S180	4	(semiconductor or die or dice or chip or IC) and (interpos$3 or interconnect$3 or redistribut$3) with spacer with (under near fill or underfill) and (under near fill or underfill) with (epoxy or polyimide)	USPAT	OR	ON	2005/06/21 13:13
S181	5	(semiconductor or die or dice or chip or IC) and (interpos$3 or interconnect$3 or redistribut$3) with spacer with (under near fill or underfill or attaching) and (under near fill or underfill or attaching) with (epoxy or polyimide)	USPAT	OR	ON	2005/06/21 13:14
S182	27	(semiconductor or die or dice or chip or IC) and (interpos$3 or interconnect$3 or redistribut$3) with spacer and (under near fill or underfill or attaching) with (epoxy or polyimide)	USPAT	OR	ON	2005/06/21 13:16

S183	36	(semiconductor or die or dice or chip or IC) and (interpos$3 or interconnect$3 or redistribut$3) same spacer and (under near fill or underfill or attaching) with (epoxy or polyimide)	USPAT	OR	ON	2005/06/21 13:27
S184	9	S183 not S182	USPAT	OR	ON	2005/06/21 13:16
S185	30	(semiconductor or die or dice or chip or IC) and (interpos$3 or interconnect$3 or redistribut$3) and spacer and (under near fill or underfill or attaching) with (epoxy or polyimide) and (under near fill or underfill or attaching) with board	USPAT	OR	ON	2005/06/21 13:22
S186	0	(semiconductor or die or dice or chip or IC) and (carrier or module) with spacer and (under near fill or underfill) with (epoxy or polyimide) and (under near fill or underfill) with board	USPAT	OR	ON	2005/06/21 13:23
S187	1	(semiconductor or die or dice or chip or IC) and (carrier or module) with stiffener and (under near fill or underfill) with (epoxy or polyimide) and (under near fill or underfill) with board	USPAT	OR	ON	2005/06/21 13:24
S188	41	(semiconductor or die or dice or chip or IC) and (carrier or module) with spacer with board and (mold$3 or encapsulat$3 or resin) with (epoxy or polyimide)	USPAT	OR	ON	2005/06/21 13:24

S189	28	(semiconductor or die or dice or chip or IC) and (interpos$3 or interconnect$3 or redistribut$3) with spacer with board and (mold$3 or encapsulat $3 or resin) with (epoxy or polyimide)	USPAT	OR	ON	2005/06/21 17:03
S190	1	"6114757".PN.	USPAT; USOCR	OR	OFF	2005/06/21 14:34
S191	1	"6175517".PN.	USPAT; USOCR	OR	OFF	2005/06/21 14:34
S192	29	(semiconductor or die or dice or chip or IC) and (interpos$3 or interconnect$3 or redistribut$3) with ground near plane with (protective or cover$)	USPAT	OR	ON	2005/06/21 15:13
S193	32	"5901041"	USPAT	OR	OFF	2005/06/21 14:49
S194	1	"6696748".pn.	USPAT	OR	OFF	2005/06/21 15:03
S195	1	"4887148".PN.	USPAT; USOCR	OR	OFF	2005/06/21 14:50
S196	1	"5627407".PN.	USPAT; USOCR	OR	OFF	2005/06/21 14:50
S197	1	"6258624".PN.	USPAT; USOCR	OR	OFF	2005/06/21 14:50
S198	1	"6291899".PN.	USPAT; USOCR	OR	OFF	2005/06/21 14:50
S199	1	"5432114".PN.	USPAT; USOCR	OR	OFF	2005/06/21 14:57
S200	1	"5477082".PN.	USPAT; USOCR	OR	OFF	2005/06/21 14:57
S201	1	"5834848".PN.	USPAT; USOCR	OR	OFF	2005/06/21 14:57
S202	1	"5834848".PN.	USPAT; USOCR	OR	OFF	2005/06/21 14:59
S203	1	"5895965".PN.	USPAT; USOCR	OR	OFF	2005/06/21 14:59
S204	1	"5900675".PN.	USPAT; USOCR	OR	OFF	2005/06/21 14:59
S205	1	"5926379".PN.	USPAT; USOCR	OR	OFF	2005/06/21 15:00
S206	1	"5926708".PN.	USPAT; USOCR	OR	OFF	2005/06/21 15:00

S207	1	"5953599".PN.	USPAT; USOCR	OR	OFF	2005/06/21 15:00
S208	1	"5990418".PN.	USPAT; USOCR	OR	OFF	2005/06/21 15:00
S209	1	"6025650".PN.	USPAT; USOCR	OR	OFF	2005/06/21 15:00
S210	1	"6078506".PN.	USPAT; USOCR	OR	OFF	2005/06/21 15:01
S211	1	"6294831".PN.	USPAT; USOCR	OR	OFF	2005/06/21 15:02
S212	1	"6316829".PN.	USPAT; USOCR	OR	OFF	2005/06/21 15:03
S213	1	"6384487".PN.	USPAT; USOCR	OR	OFF	2005/06/21 15:03
S214	40	"5834848"	USPAT	OR	OFF	2005/06/21 15:13
S215	1	"5473512".PN.	USPAT; USOCR	OR	OFF	2005/06/21 15:09
S216	1	"5640051".PN.	USPAT; USOCR	OR	OFF	2005/06/21 15:09
S217	1	"5729440".PN.	USPAT; USOCR	OR	OFF	2005/06/21 15:09
S218	1	"5731630".PN.	USPAT; USOCR	OR	OFF	2005/06/21 15:09
S219	4881	(semiconductor or die or dice or chip or IC) and (interpos$3 or interconnect$3 or redistribut$3) with (buffer or stabiliz$3)	USPAT	OR	ON	2005/06/21 15:13
S220	39	(semiconductor or die or dice or chip or IC) and (interpos$3 or interconnect$3 or redistribut$3) with (buffer or stabiliz$3) near (plate or plane or layer) with (underfill or adhes$3 or resin or epoxy or polyimide)	USPAT	OR	ON	2005/06/21 15:16
S221	209	(semiconductor or die or dice or chip or IC) and (interpos$3 or interconnect$3 or redistribut$3) with (buffer or stabiliz$3) and (buffer or stabiliz $3) with (underfill or adhes$3 or resin or epoxy or polyimide)	USPAT	OR	ON	2005/06/21 15:25

S222	219411	"5834848" and (interpos $3 or interconnect$3 or redistribut$3) and (buffer or stabiliz$3) and (buffer or stabiliz $3) with (underfill or adhes$3) and (adhesive or underfill) (epoxy or polyimide)	USPAT	OR	ON	2005/06/21 15:26
S223	1	"5834848" and (interpos $3 or interconnect$3 or redistribut$3) and (buffer or stabiliz$3) and (buffer or stabiliz $3) with (underfill or adhes$3) and (adhesive or underfill) with (epoxy or polyimide)	USPAT	OR	ON	2005/06/21 15:26
S224	3	"5834848" and (interpos $3 or interconnect$3 or redistribut$3) and (buffer or stabiliz$3) and (buffer or stabiliz $3) with (underfill or adhes$3)	USPAT	OR	ON	2005/06/21 15:27
S225	3	"5834848" and (interpos $3 or interconnect$3 or redistribut$3) and (buffer or stabiliz$3) and (adhes$3) with (epoxy or polyimide)	USPAT	OR	ON	2005/06/21 16:06
S226	6999	(semiconductor or die or chip) and flux with material	USPAT	OR	ON	2005/06/21 16:07
S227	958	(semiconductor or die or chip) and flux with (dielectric or insulating)	USPAT	OR	ON	2005/06/21 16:07
S228	94	(semiconductor or die or chip) with flux with (dielectric or insulating)	USPAT	OR	ON	2005/06/21 16:08
S229	6	(semiconductor or die or chip) with flux with contain$3 with (dielectric or insulating)	USPAT	OR	ON	2005/06/21 16:09
S230	5	(semiconductor or die or chip) with flux with made with (dielectric or insulating)	USPAT	OR	ON	2005/06/21 16:10

S231	11	(semiconductor or die or chip) with flux with made with (resin or epoxy)	USPAT	OR	ON	2005/06/21 16:12
S232	1	(semiconductor or die or chip) with flux near material with (resin or epoxy)	USPAT	OR	ON	2005/06/21 16:13
S233	0	(semiconductor or die or chip) with liquid near flux near material with (resin or epoxy)	USPAT	OR	ON	2005/06/21 16:13
S234	0	(semiconductor or die or chip) with liquid near flux with (resin or epoxy)	USPAT	OR	ON	2005/06/21 16:14
S235	11	liquid near flux with (resin or epoxy)	USPAT	OR	ON	2005/06/21 16:14
S236	22	(semiconductor or die or dice or chip or IC) and (interpos$3 or interconnect$3 or redistribut$3) with underfill with board and (underfill) with (epoxy or polyimide)	USPAT	OR	ON	2005/06/21 17:40
S237	186	(semiconductor or die or dice or chip or IC) and (interpos$3 or interconnect$3 or redistribut$3) with adhesive with board and (adhesive) with (epoxy or polyimide)	USPAT	OR	ON	2005/06/21 18:22
S238	407	257/729	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/21 18:28
S239	4481	257/778	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/21 18:29
S240	449	257/729	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/27 20:25

S241	5051	257/778	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/27 20:34
S242	2645	257/786	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/27 21:20
S243	2	"6291899".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/27 20:36
S244	3	257/e21.504	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/27 21:21
S245	53	("5473512" | "5640051" | "5729440" | "5731630").PN. OR ("5834848").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/30 18:45
S246	23	("3869787" | "5410185" | "5677575" | "5682297" | "5834848" | "5892289" | "5936304" | "5962925" | "5969426" | "5973930" | "6094155" | "6139978" | "6174751" | "6177724" | "6225433").PN. OR ("6303998").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/30 19:12
S247	14	("5834848" | "5959362").PN. OR ("6081038").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/30 19:14
S248	45	("4771330" | "5045921" | "5222014" | "5239198" | "5477082" | "5646828" | "5834848").PN. OR ("5901041").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/30 19:10
S249	24	("3777221" | "5375042" | "5477933" | "5535101").PN. OR ("5973930").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/30 19:16

S250	20	("4642163" | "4867839" | "5011066" | "5489750" | "5973406" | "6081038" | "6142609" | "6222277" | "6225702").PN. OR ("6346679").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/30 19:20
S251	159	("4744007" | "4868712" | "5155302" | "5354955").PN. OR ("5477933").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/30 19:20
S252	39	("4489364" | "4549200" | "4652065" | "4706165" | "4803595" | "4922377" | "4926241" | "5036163" | "5060116" | "5066831" | "5243140" | "5294754").PN. OR ("5354955").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/30 19:25
S253	32	(flip near chip) same interposer same board and solder near (resist $3 or mask$3)	USPAT	OR	ON	2006/09/30 19:57
S254	35	("3868724" | "4710798" | "5019673" | "5159535" | "5346861" | "5352926" | "5384955" | "5491303" | "5504035" | "5585162" | "5602419" | "5615477" | "5616958" | "5636996" | "5637920" | "5674785" | "5686764" | "5699613" | "5708296" | "5714800" | "5719749" | "5729894" | "5777386" | "5790378" | "5798567" | "5866949" | "5909010" | "5925930" | "5962925" | "6075710" | "6098282" | "6192581" | "6281448").PN. OR ("6507118").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/30 19:54

S255	33	(flip near chip) same interposer same (board or PCB orPWB) and solder near (resist$3 or mask$3)	USPAT	OR	ON	2006/09/30 21:15
S256	33	((flip or "C4") near chip) same interposer same (board or PCB orPWB) and solder near (resist$3 or mask$3)	USPAT	OR	ON	2006/09/30 19:59
S257	92	(flip or "C4") with (chip or die or semiconductor or IC) and (semiconductor or die or chip or IC) same interposer same (board or PCB orPWB) and solder near (resist$3 or mask$3)	USPAT	OR	ON	2006/09/30 20:00
S258	59	S257 not S256	USPAT	OR	ON	2006/09/30 20:08
S259	470	257/729	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/30 20:36
S260	319	(semiconductor or die or chip or IC) and solder near mask with polyimide	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/30 20:33
S261	14	(semiconductor or die or chip or IC) and interposer same solder near mask with polyimide	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/30 20:34
S262	12	(semiconductor or die or chip or IC) and interconnect$3 same solder near mask with polyimide	USPAT	OR	ON	2006/09/30 20:40
S263	5476	257/778	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/30 22:02

S264	2	"6020637".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/30 20:40
S265	0	"6020637".pn. and solder near mask with polyimide	USPAT	OR	ON	2006/09/30 20:40
S266	1	"6020637".pn. and solder near mask and polyimide	USPAT	OR	ON	2006/09/30 20:40
S267	28	S257 and copper with pad	USPAT	OR	ON	2006/09/30 21:15
S268	4	257/E23.062	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/30 22:03
S269	25	257/E23.069	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/30 22:04
S270	12	257/E23.07	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/30 22:04
S271	47	(interpos$3 or interconnect$3 or redistribut$3) with strain with thermal near cycling	USPAT	OR	ON	2007/02/26 18:48
S272	0	(interpos$3 or interconnect$3 or redistribut$3) with strain with thermal near cycling with ("C" or "F" or celsius or fahrenheit)	USPAT	OR	ON	2007/02/26 19:00
S273	0	(interpos$3 or interconnect$3 or redistribut$3) with strain with thermal near cycling with ("C" or "F" or celsius or fahrenheit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/26 19:01

S274	0	(interpos$3 or interconnect$3 or redistribut$3 or substrate or borad or carrier) with strain with thermal near cycling with ("C" or "F" or celsius or fahrenheit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/26 19:01
S275	0	(interpos$3 or interconnect$3 or redistribut$3 or substrate or broad or carrier) with strain with thermal near cycling with ("C" or "F" or celsius or fahrenheit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/26 19:01
S276	6	(interpos$3 or interconnect$3 or redistribut$3 or substrate or broad or carrier) same strain with thermal near cycling with ("C" or "F" or celsius or fahrenheit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/26 19:02
S277	37	(interpos$3 or interconnect$3 or redistribut$3 or substrate or broad or carrier) same (strain or stress) with thermal near cycling with ("C" or "F" or celsius or fahrenheit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/26 20:23
S278	6	257/e23.062	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/26 20:24
S279	43	257/e23.069	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/26 20:25
S280	20	257/e23.07	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/26 20:27

S281	499	257/729	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/26 20:37
S282	5774	257/778	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/26 20:41
S283	2966	257/786	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/26 20:41
S284	0	(interpos$3 or interconnect$3 or redistribut$3 or substrate or board or carrier or module) with (reduc$3 or decreas$3) with (thermal or heat) near missmatch$3 with (reduc$3 or decreas$3) with crack$3	USPAT	OR	ON	2007/03/29 16:43
S285	0	(interpos$3 or interconnect$3 or redistribut$3 or substrate or board or carrier or module) same (reduc$3 or decreas$3) with (thermal or heat) near missmatch$3 with (reduc$3 or decreas$3) with crack$3	USPAT	OR	ON	2007/03/29 16:43
S286	0	(interpos$3 or interconnect$3 or redistribut$3 or substrate or board or carrier or module) same (reduc$3 or decreas$3) with (thermal or heat) near missmatch$3 same (reduc$3 or decreas$3) with crack$3	USPAT	OR	ON	2007/03/29 16:43

S287	0	(interpos$3 or interconnect$3 or redistribut$3 or substrate or board or carrier or module) and (reduc$3 or decreas$3) with (thermal or heat) near missmatch$3 same (reduc$3 or decreas$3) with crack $3	USPAT	OR	ON	2007/03/29 16:43
S288	0	(interpos$3 or interconnect$3 or redistribut$3 or substrate or board or carrier or module) and (reduc$3 or decreas$3) with (thermal or heat) near missmatch$3 same (reduc$3 or decreas$3) with crack $3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/29 16:44
S289	0	(interpos$3 or interconnect$3 or redistribut$3 or substrate or board or carrier or module) and (reduc$3 or decreas$3) with (thermal or heat) with missmatch$3 same (reduc$3 or decreas$3) with crack $3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/29 16:44
S290	0	(interpos$3 or interconnect$3 or redistribut$3 or substrate or board or carrier or module) and (reduc$3 or decreas$3) with (thermal or heat) with missmatch$3 and (reduc$3 or decreas$3) with crack$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/29 16:44
S291	0	(interpos$3 or interconnect$3 or redistribut$3 or substrate or board or carrier or module) and (reduc$3 or decreas$3) and (thermal or heat) with missmatch$3 and (reduc$3 or decreas$3) with crack$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/29 16:45

S292	2333	(interpos$3 or interconnect$3 or redistribut$3 or substrate or board or carrier or module) and (reduc$3 or decreas$3) with (thermal or heat) with (missmatch$3 or expans$3) and (reduc $3 or decreas$3) with crack$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/29 16:46
S293	0	(interpos$3 or interconnect$3 or redistribut$3 or substrate or board or carrier or module) and (reduc$3 or decreas$3) and (thermal or heat) with (missmatch$3) and (reduc$3 or decreas $3) with crack$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/29 16:48
S294	0	(interpos$3 or interconnect$3 or redistribut$3 or substrate or board or carrier or module) and (reduc$3 or decreas$3) and (thermal or heat) with (missmatch$3) same crack$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/29 16:47
S295	0	(interpos$3 or interconnect$3 or redistribut$3 or substrate or board or carrier or module) and (thermal or heat) with (missmatch$3) same crack$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/29 16:47
S296	0	(interpos$3 or interconnect$3 or redistribut$3 or substrate or board or carrier or module) and (thermal or heat) with (missmatch$3) and crack$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/29 16:47

S297	3250	(interpos$3 or interconnect$3 or redistribut$3 or substrate or board or carrier or module) and (reduc$3 or decreas$3) and (thermal or heat) with differenc$3 and (reduc$3 or decreas$3) with crack$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/29 16:48
S298	1177	(interpos$3 or interconnect$3 or redistribut$3 or substrate or board or carrier or module) and (reduc$3 or decreas$3) with (thermal or heat) with differenc$3 and (reduc$3 or decreas$3) with crack$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/29 16:49
S299	568	(interpos$3 or interconnect$3 or redistribut$3 or substrate or board or carrier or module) and (reduc$3 or decreas$3) with (thermal or heat) with differenc$3 same (reduc$3 or decreas$3) with crack$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/29 16:49
S300	330	(interpos$3 or interconnect$3 or redistribut$3 or substrate or board or carrier or module) same (reduc$3 or decreas$3) with (thermal or heat) with differenc$3 same (reduc$3 or decreas$3) with crack$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/29 16:50
S301	53	(interpos$3 or interconnect$3 or redistribut$3 or substrate or board or carrier or module) same (reduc$3 or decreas$3) with (thermal or heat) with differenc$3 same (reduc$3 or decreas$3) with crack$3 same (semiconductor or die or dice or chip or IC)	USPAT	OR	ON	2007/03/29 16:55

S302	105	(interpos$3 or interconnect$3 or redistribut$3 or substrate or board or carrier or module) same (reduc$3 or decreas$3) with (thermal or heat) with differenc$3 same (reduc$3 or decreas$3) with crack$3 and (semiconductor or die or dice or chip or IC)	USPAT	OR	ON	2007/03/29 17:05
S303	98	S302 and (interpos$3 or interconnect$3 or redistribut$3 or substrate or board or carrier or module) with crack$3	USPAT	OR	ON	2007/03/29 16:58
S304	95	S303 and (interpos$3 or interconnect$3 or redistribut$3 or substrate or board or carrier or module) with (thermal or heat) with differenc$3	USPAT	OR	ON	2007/03/29 16:58
S305	29	S302 and (interpos$3 or interconnect$3 or redistribut$3 or board or carrier or module) with crack$3	USPAT	OR	ON	2007/03/29 16:58
S306	28	S305 and (interpos$3 or interconnect$3 or redistribut$3 or substrate or board or carrier or module) with (thermal or heat) with differenc$3	USPAT	OR	ON	2007/03/29 16:58
S307	456	(interpos$3 or interconnect$3 or redistribut$3 or substrate or board or carrier or module) same (reduc$3 or decreas$3 or prevent$3) with (thermal or heat) with stress same (reduc$3 or decreas$3 or prevent$3) with crack$3 and (semiconductor or die or dice or chip or IC)	USPAT	OR	ON	2007/03/29 17:06

S308	48	(interpos$3 or interconnect$3 or redistribut$3 or substrate or board or carrier or module) with (reduc$3 or decreas$3) with (thermal or heat) with stress same (reduc$3 or decreas$3 or prevent$3) near crack$3 and (semiconductor or die or dice or chip or IC)	USPAT	OR	ON	2007/03/29 17:07
S309	30	(interpos$3 or interconnect$3 or redistribut$3 or substrate or board or carrier or module) with (reduc$3 or decreas$3) with (thermal or heat) near stress same (reduc$3 or decreas$3 or prevent$3) near crack$3 and (semiconductor or die or dice or chip or IC)	USPAT	OR	ON	2007/03/29 17:10
S310	14	(interpos$3 or interconnect$3 or redistribut$3 or ceramic near substrate or board or carrier or module) with (reduc$3 or decreas$3) with (thermal or heat) near stress same (reduc$3 or decreas$3 or prevent$3) near crack$3 and (semiconductor or die or dice or chip or IC)	USPAT	OR	ON	2007/03/29 17:10
S311	19	257/E23.062	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/20 18:52
S312	84	257/E23.069	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/20 18:52

S313	26	257/E23.07	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/20 18:53
S314	6227	257/778	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/20 18:55
S315	3162	257/786	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/20 19:55
S316	514	257/729	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/20 19:55

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